


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	MDG/22/13640	
<b>1.3 Title of PCN</b>	STM32G070x, STM32G071x and STM32G081x - product enhancement	
<b>1.4 Product Category</b>	STM32G070CBxx STM32G070KBxx STM32G070RBxx STM32G071x8xx STM32G071xBxx STM32G081xBxx	
<b>1.5 Issue date</b>	2022-11-24	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	NEMETH KRISZTINA
<b>2.1.2 Phone</b>	+49 89460062210
<b>2.1.3 Email</b>	krisztina.nemeth@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Ricardo Antonio DE SA EARP
<b>2.1.2 Marketing Manager</b>	Veronique BARLATIER
<b>2.1.3 Quality Manager</b>	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	TSMC FAB14 (Taiwan) ST Crolles (France)

**4. Description of change**

	Old	New
<b>4.1 Description</b>	STM32G070x, STM32G071x and STM32G081x 128K - (Die460- cut2.0 revision B) product has limitation as described in Errata Sheets. - ES0468 (Rev 3 - February 2021) STM32G070CB/KB/RB device errata - ES0418 (Rev 3 - February 2021) STM32G071xx device errata - ES0412 (Rev 3 - February 2021) STM32G081xB device errata	STM32G070x, STM32G071x and STM32G081x 128K - (Die460- cut2.1 revision Y) product has limitation as described in Errata Sheets. - ES0468 (Rev 4 - October 2022) STM32G070CB/KB/RB device errata - ES0418 (Rev 4 - October 2022) STM32G071xx device errata - ES0412 (Rev 4 - October 2022) STM32G081xB device errata
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	Impact on functionality as indicated in Errata Sheets: ES0468, ES0418 & ES0412	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Improvements was implemented to increase robustness, performances and quality of our products.
<b>5.2 Customer Benefit</b>	SERVICE IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	Traceability ensured by ST internal tools. Die revision changes from "B" to "Y" on Package Marking
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2022-12-20
<b>7.2 Intended start of delivery</b>	2022-12-20

7.3 Qualification sample available?	Upon Request
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8. Qualification / Validation			
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8.1 Description	13640 PCN13640_RERMCD1602_TM32G0 128K - ORCA Zero 128K - die 460 - MCD QA reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2022-11-24

9. Attachments (additional documentations)			
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13640 Public product.pdf 13640 PCN13640_RERMCD1602_TM32G0 128K - ORCA Zero 128K - die 460 - MCD QA reliability plan.pdf 13640 PCN13640_Additional information.pdf			
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10. Affected parts		
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10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32G070CBT6	
	STM32G070RBT6	
	STM32G071CBT6	
	STM32G071KBT6	
	STM32L151QCH6	
	STM32L151QDH6	
	STM32L151RCY6TR	
	STM32L151RDT6	
	STM32L151RDT7	
	STM32L151VDT6	
	STM32L151ZCT6	
	STM32L152RDT6	
	STM32L152ZCT6	
	STM32L152ZDT6	
	STM32L162QDH6	
	STM32L162ZDT6	

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